

# KYOCERA KE-850SP

Epoxy; Epoxide

KYOCERA Chemical Corporation

## Message:

Developed for Power Device Package that needs Good Heat Dissipation Through Molding Compound.

Strong Points

High Thermal Conductivity with Good Moldability, Excellent Moisture Resistance and Low Stress.

Used in Auto Molding System by Rapid Cure Grades.

KE-870 and KE-880 is Formulated with Special High Thermal Conductivity Filler System and Achieve High Thermal Conductivity (above 3W/m K).

Application

Isolation Packages such as TO-220 and TO-3P that need Heat Dissipation Characteristics.

Packages for High Heating Volume such as Power Module.

General Information		
Features	Good Moldability	
	Moisture Resistant	
	Thermally Conductive	
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	2.19	g/cm <sup>3</sup>
Spiral Flow	50.0	cm
Thermal	Nominal Value	Unit
Glass Transition Temperature	190	°C
CLTE - Flow		
-- 1	2.1E-5	cm/cm/°C
-- 2	5.9E-5	cm/cm/°C
Thermal Conductivity	2.3	W/m/K
Uncured Properties	Nominal Value	Unit
Gel Time	0.58	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

The information and data on this page are provided by manufacturers and document providers. SHANGHAI SUSHENG assumes no legal liability. It is strongly recommended to verify all technical data with material suppliers before final material selection. All rights belong to the original authors. If any infringement occurs, please contact us immediately.

## Recommended distributors for this material

### Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China

